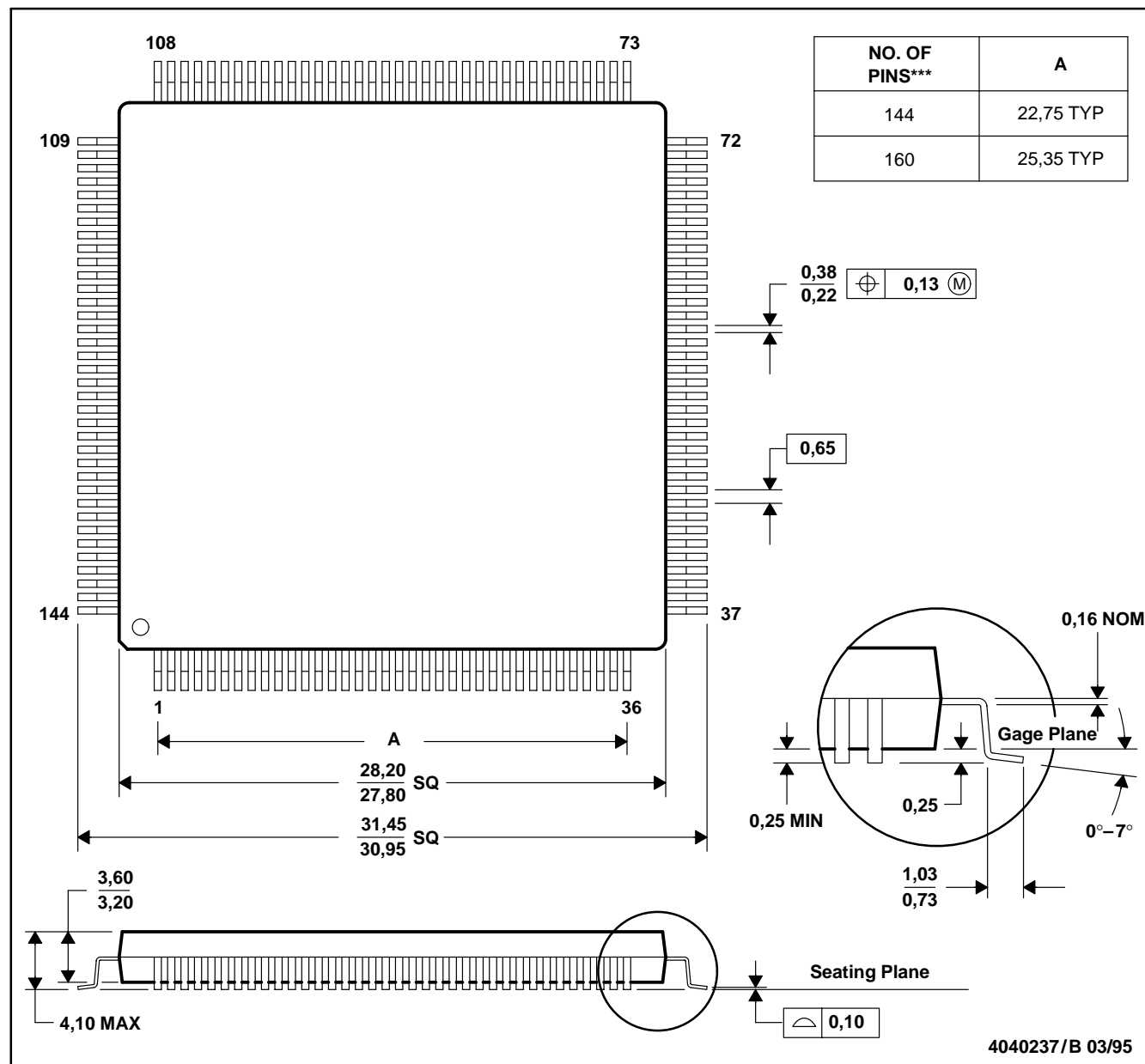


## PCE (S-PQFP-G\*\*\*)

## PLASTIC QUAD FLATPACK

144 PIN SHOWN



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Thermally enhanced molded plastic package with a heat spreader (HSP)
  - Falls within JEDEC MS-022
  - The 144 PCE is identical to the 160 PCE except that four leads per corner are removed.

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